



US00D348391S

# United States Patent [19]

[11] Patent Number: **Des. 348,391**

Ichikawa et al.

[45] Date of Patent: **\*\* Jul. 5, 1994**

[54] **PACKAGE FOR A HEADPHONE**

4,319,684	3/1982	Backman et al.	206/464
4,781,289	11/1988	Perkins	206/461 X
4,901,858	2/1990	Anderson	206/461

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**OTHER PUBLICATIONS**

Modern Packaging, 1978, p. 300, as shown.  
Hardware Age, Sep. 1984, p. 60 as shown.

[73] Assignee: **Sony Corporation**, Tokyo, Japan

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[\*\*] Term: **14 Years**

[57] **CLAIM**

[21] Appl. No.: **5,419**

The ornamental design for a package for a headphone, as shown.

[22] Filed: **Mar. 4, 1993**

[52] U.S. Cl. .... **D9/415**

**DESCRIPTION**

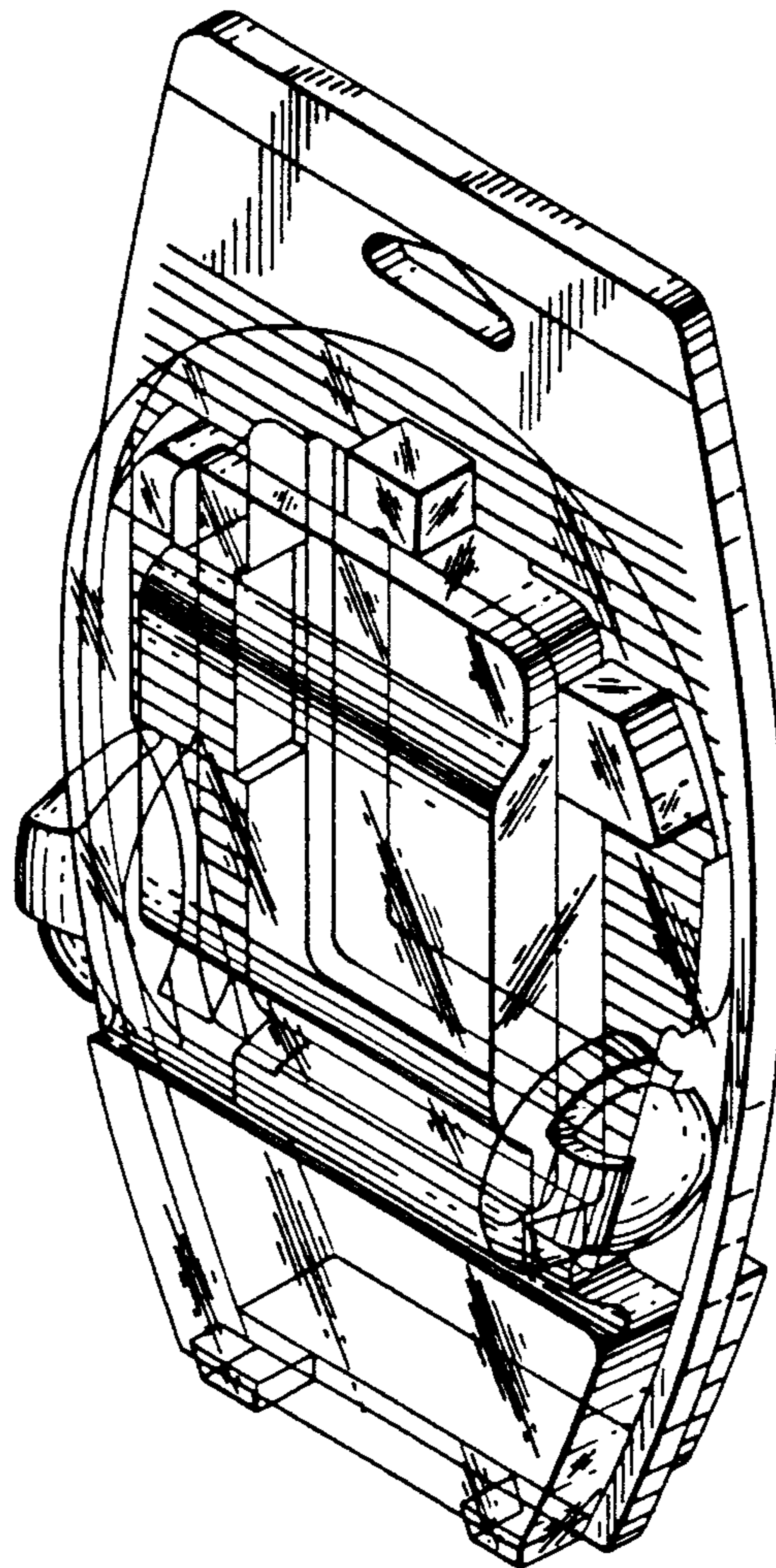
[58] Field of Search ..... D9/415, 418, 337, 341;  
206/461-471, 806, 216, 316.1, 307, 495

FIG. 1 is a top, front and right-side perspective view of a package for a headphone, showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a left-side elevational view thereof; FIG. 5 is a right-side elevational view thereof; FIG. 6 is a top plan view thereof; and, FIG. 7 is a bottom plan view thereof.

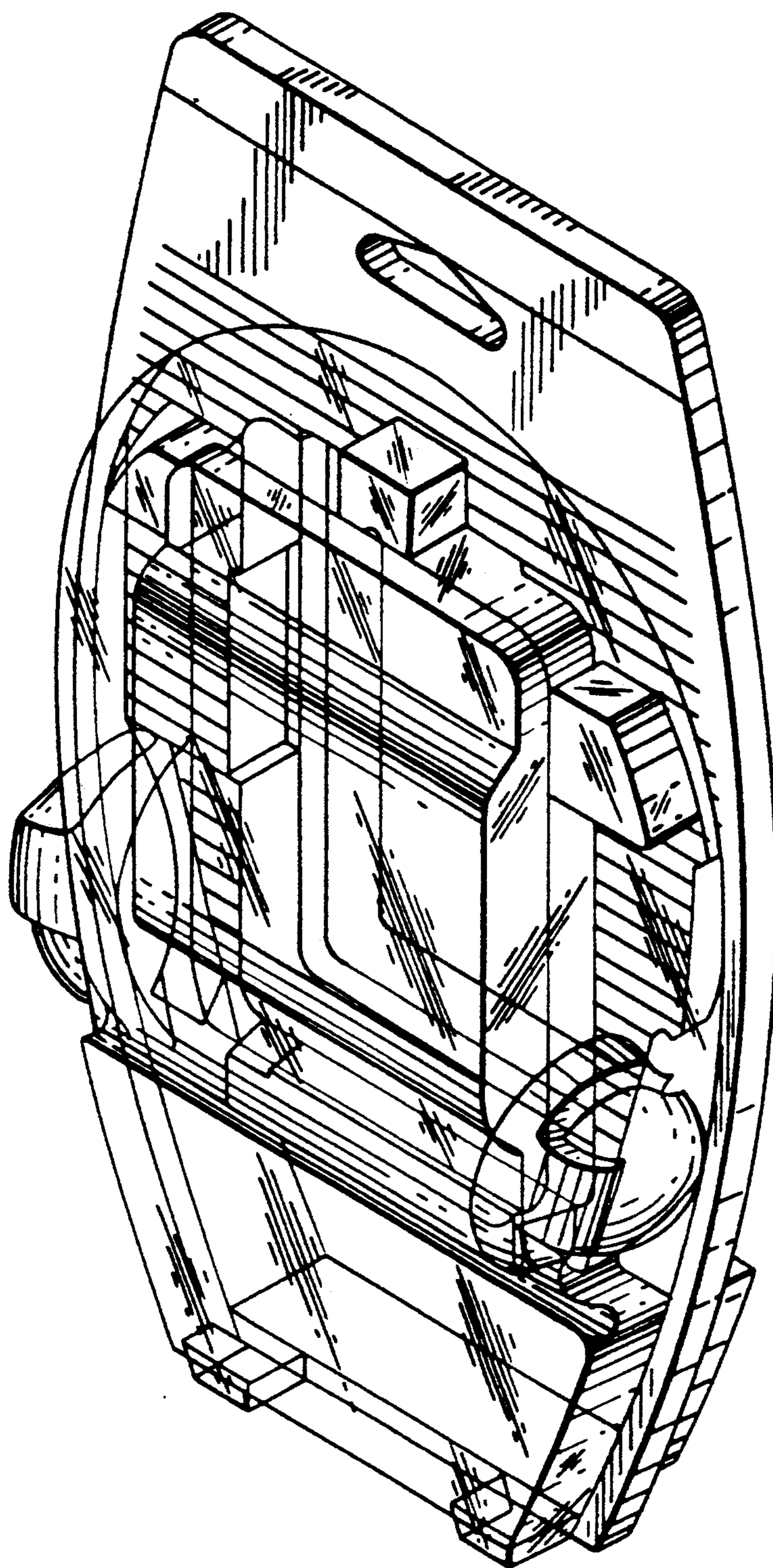
[56] **References Cited**

**U.S. PATENT DOCUMENTS**

D. 291,064	7/1987	Haber et al.	D9/415
D. 321,323	11/1991	Nakamura	D9/415
D. 341,777	11/1993	Sheu	D9/341 X



*FIG. 1*





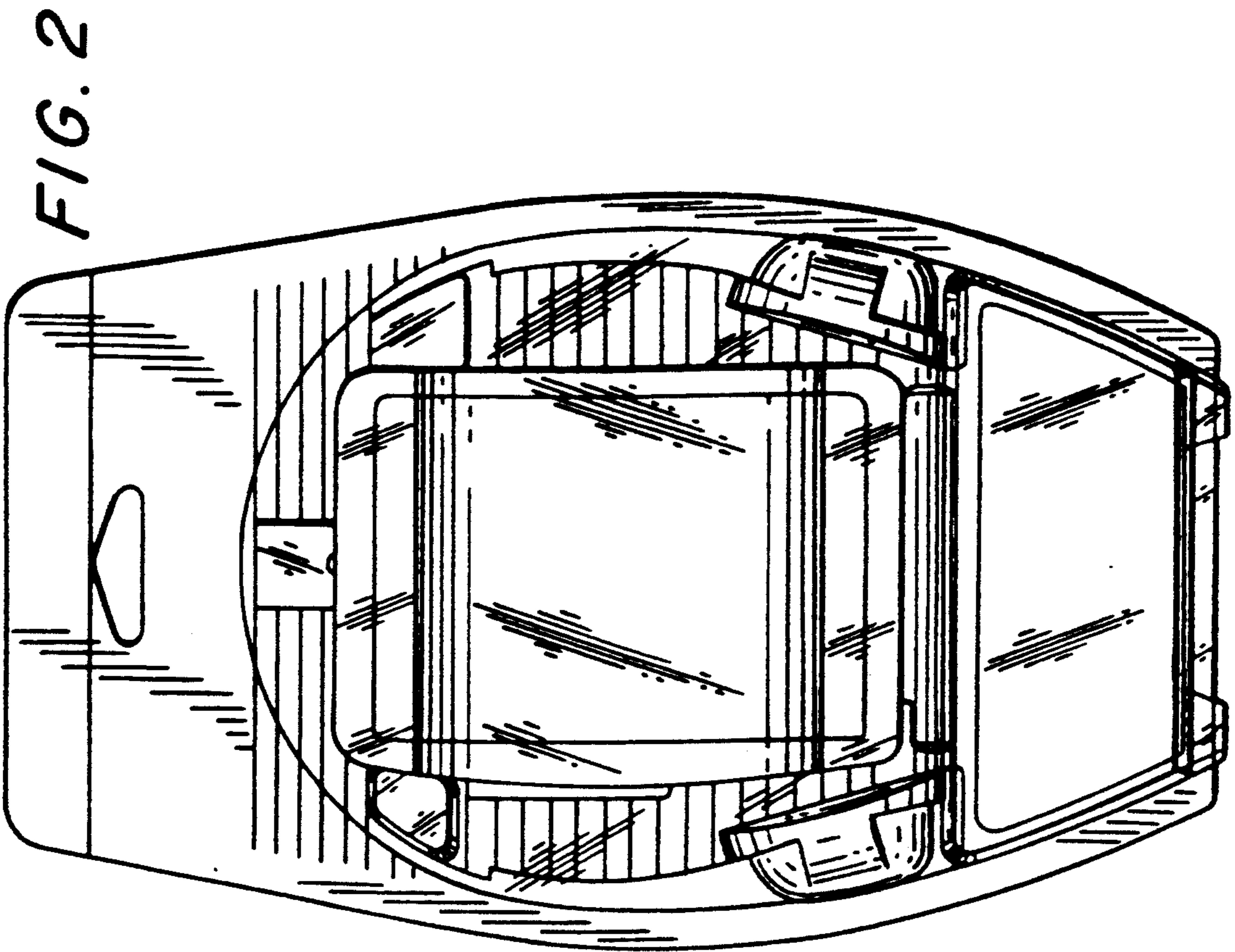
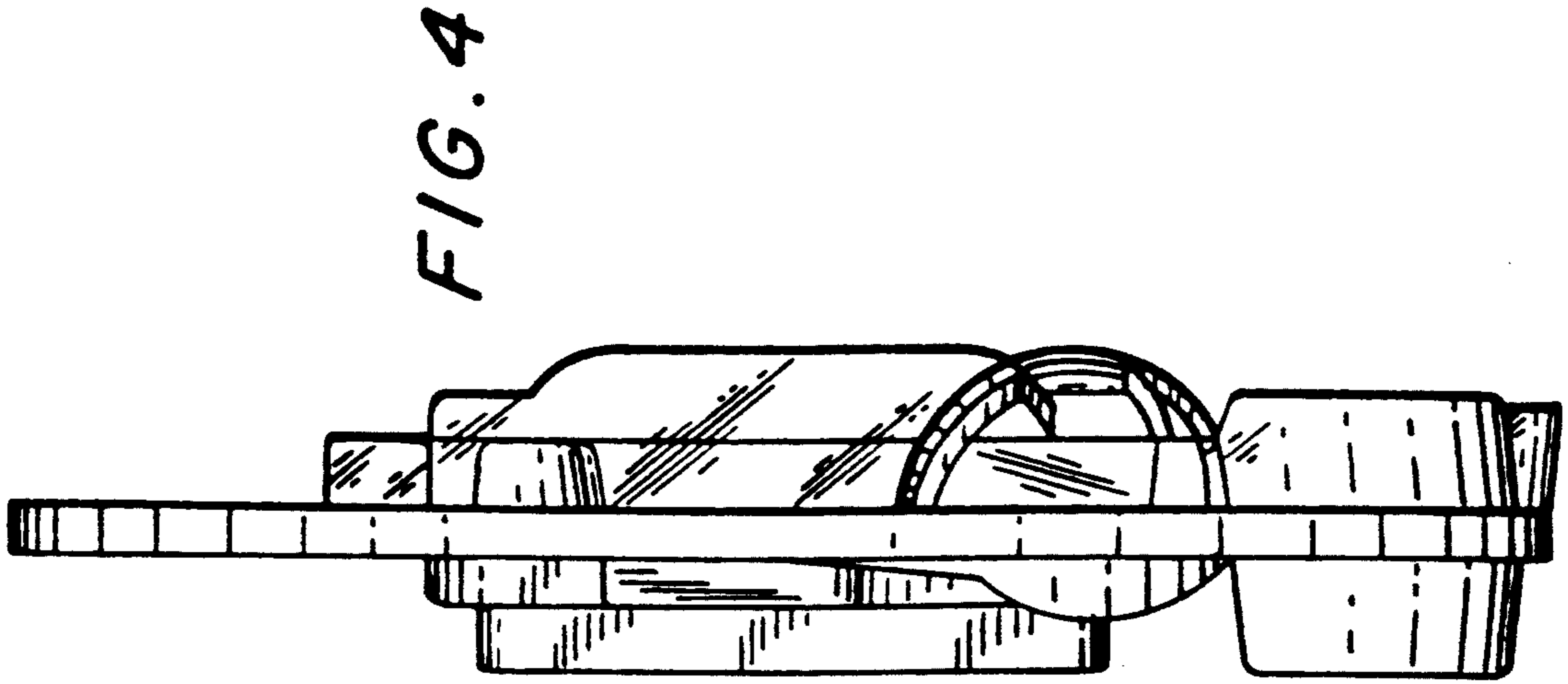


FIG. 3

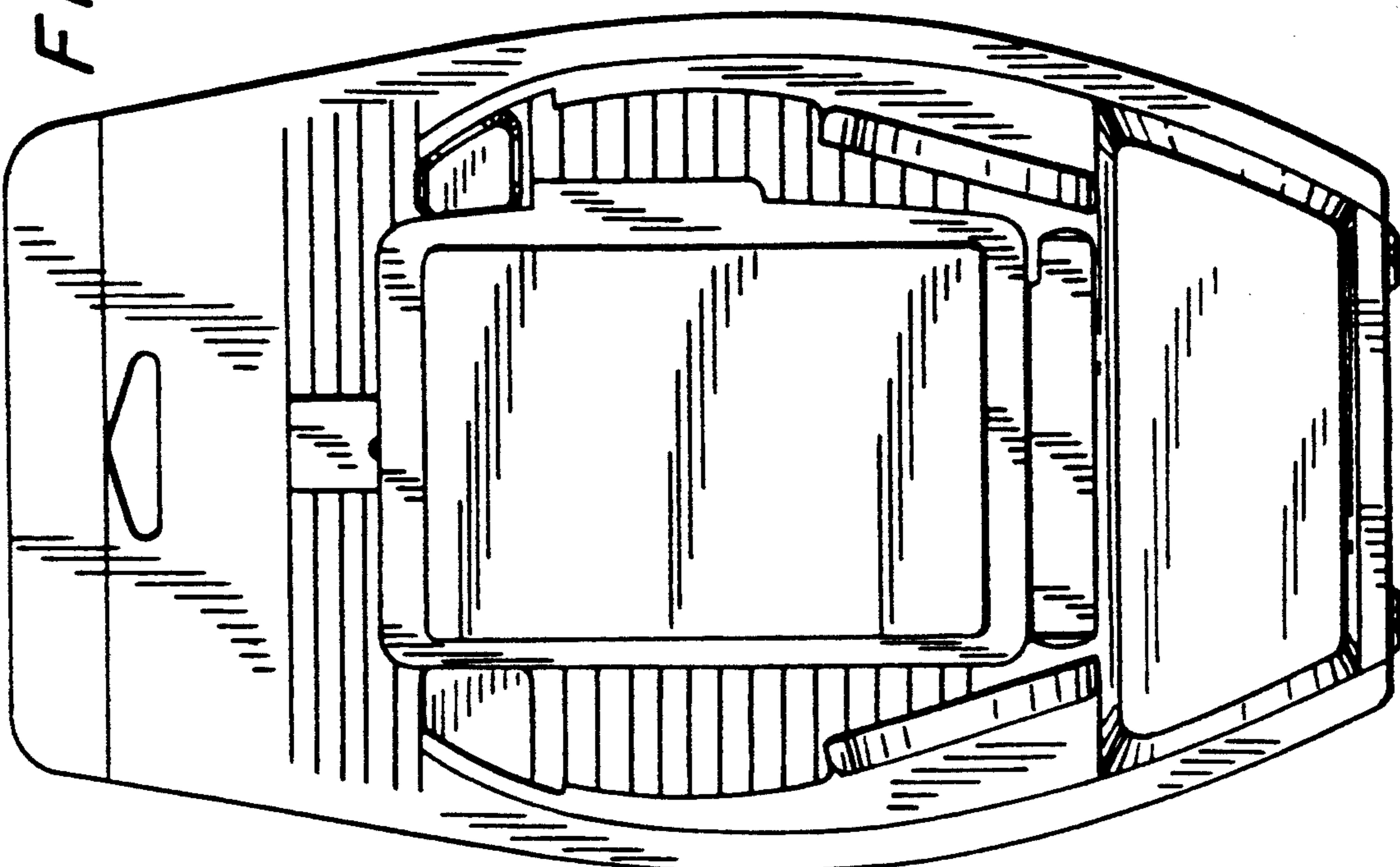
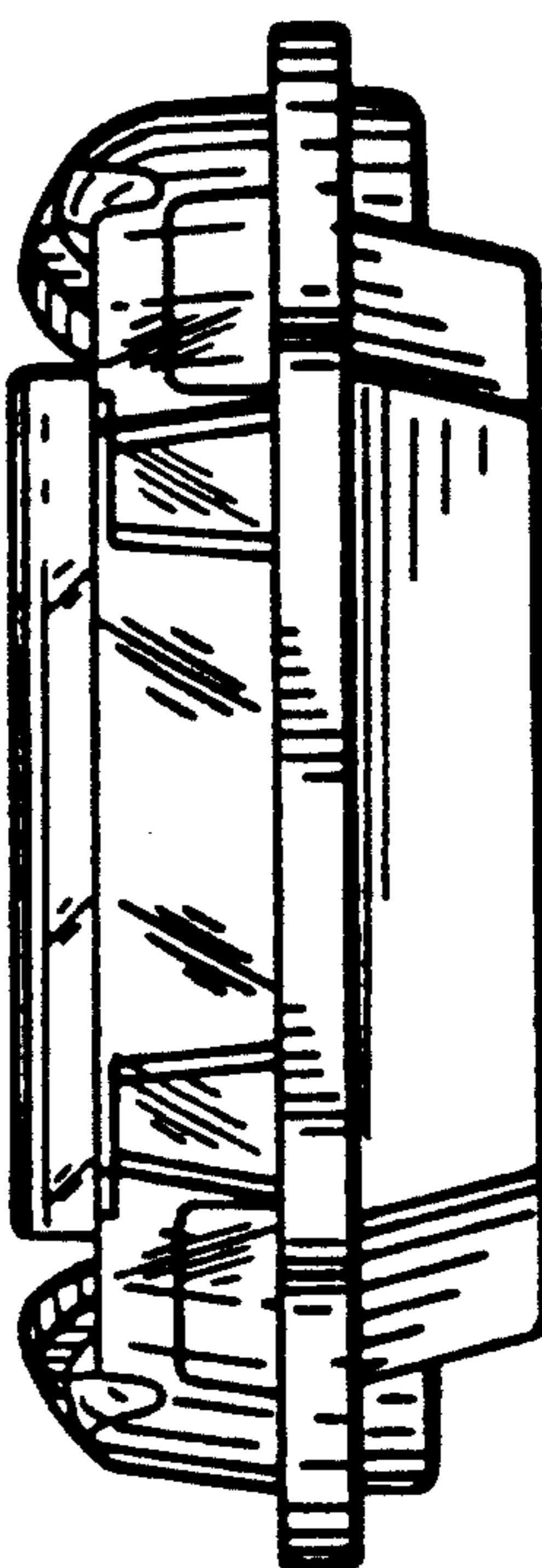
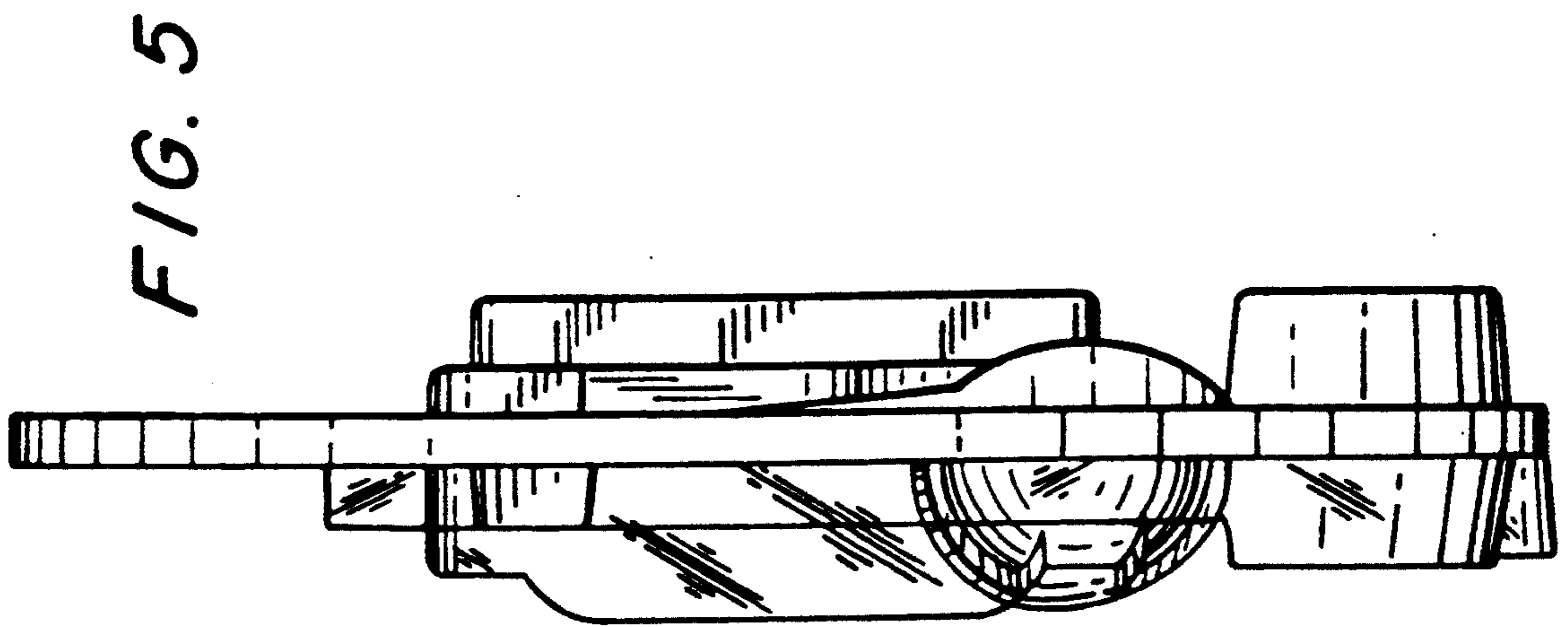


FIG. 7





*FIG. 6*

